



REVISIONS				
ZONE	LTR	DESCRIPTION	DATE	APPROVED
-		PRODUCTION RELEASE PER EO #11098	DATE OF EO	R. J.
A		REV PER EO #12095	08-11-05	R. J.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	-	2.44	2.68	-	.096	.105
A1	1.48	1.65	1.82	.058	.065	.072
b	0.63	0.68	0.73	.025	.027	.029
D E	29.00			1.142		
D1 E1	27.00			1.063		
e	1.00			0.040		
S	0.500			0.020		
aaa	0.20			0.008		
bbb	0.10			0.004		
ddd	0.10			0.004		
eee	0.25			0.010		
fff	0.10			0.004		

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS.
2. DISTANCE FROM THE BOTTOM OF THE CERAMIC TO THE HIGHEST POINT OF THE PACKAGE INCLUDES PACKAGE BODY THICKNESS A1, AND CHIP HEIGHT.
3. THE A-1 CORNER IS IDENTIFIED BY A SMALLER CHAMFER, AND A 0.4mm DOT ON THE TOP SURFACE, AND A MISSING LGA PAD ON THE BOTTOM SURFACE.
4. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
5. b= DIAMETER OF THE METALIZED LGA PAD.
6. DFOISR 05-S-1874.

REFERENCE ONLY COPY

		T. WAGNER	1/27/05	HONEYWELL INC.		
		DRAFTSPERSON	DATE	SOLID STATE ELECTRONICS CENTER		
				MINNEAPOLIS, MINNESOTA		
		CHECKER	DATE	783 FLIP CHIP LGA		
		R. JENSEN	1/31/05	CASE OUTLINE		
		ENGINEERING AREA APPROVER	DATE			
		B. WESTBERG	1/31/05	SIZE	CODE IDENT NO.	DRAWING NO.
		AFFECTED AREA APPROVER	DATE	B	34168	22028760
NEXT ASSY	USED ON	L. CHAMAS	2/1/05	SCALE	NONE	SHEET 1 OF 1
APPLICATION		QUALITY APPROVER	DATE			

September 08, 2005 10:41

BOTTOM VIEW